



## **NEWS ANNOUNCEMENT**

## **FOR IMMEDIATE RELEASE**

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### **Symwave Demonstrates World's First USB 3.0 Physical Layer Device**

*Live Demonstration Coincides with Release of USB 3.0 Specification at SuperSpeed USB Developers Conference*

**SAN JOSE, Calif., November 17, 2008** – Symwave, Inc., a semiconductor supplier of high-performance analog/mixed-signal connectivity solutions for the PC, consumer and mobile devices, today announced it is demonstrating the world's first physical layer device (PHY) designed specifically to comply with the USB 3.0 specification. The live demonstration, at full 5Gbps speed, is 10 times faster than today's fastest USB devices, and will be conducted at the same time as the first public release of the Revision 1.0 Specification at the SuperSpeed USB Developers Conference at the Doubletree Hotel in San Jose, California. SuperSpeed USB is backwards compatible with over 10 billion USB devices shipped to-date, but enables up to 10 times faster connections, while also improving power consumption. The USB 3.0 contributors group comprises over 200 companies including the leading brands in consumer electronics, mobile devices, storage, and PCs. With such broad industry momentum and support, SuperSpeed USB is poised to become the most pervasive high-speed connectivity technology over the coming years.

Symwave's Quasar PHY is targeted at fast-growing "sync-and-go" applications, such as external storage, portable phones and media players, HD camcorders, and other applications requiring high-speed data transfer capabilities. The live demonstration to Symwave's customers, strategic partners and press will showcase Quasar's low power and exceptional jitter performance utilizing Symwave's patented intellectual property and high-speed mixed-signal design methodologies.

"With more than 2.6 Billion USB ports shipped in 2007 alone, the market opportunity for USB 3.0 should eclipse all other wired interconnect technologies combined," said Brian O'Rourke, senior analyst with In-Stat. "According to our April-2008 report titled **Wired USB 2008:**

**SuperSpeed is Coming**, the expected compounded annual growth rate for USB 3.0 from 2009-2012 is over 100%, reaching over 500,000,000 devices in 2012. The public release of the Revision 1.0 specification today and the actual silicon availability from Symwave are two catalysts for the rapid market adoption we projected.”

“It is a strong endorsement of SuperSpeed USB and the contributors’ group involvement to see such early SuperSpeed USB development taking place,” said Jeff Ravencraft, USB-IF president and chairman. “Symwave's participation in the USB ecosystem will support the broad adoption of SuperSpeed USB.”

“Symwave is delighted to achieve the world’s first public demonstration of a USB 3.0 PHY device,” said Yossi Cohen, President and CEO of Symwave. “This is an amazing achievement by our engineering team, and underscores our mixed-signal core competency. Symwave is focused on delivering state-of-the-art USB 3.0 semiconductor solutions that will enable consumers to enjoy up to 10 times speed improvement in every consumer, storage, and connectivity device.”

Parties interested in viewing Symwave’s technology demonstration may contact John O’Neill, Symwave’s Vice President of Marketing.

### **About the SuperSpeed USB Developers Conference**

The conference is designed to provide attendees with the first opportunity to hear directly from the creators of the USB 3.0 specification, which is the technical map for device manufacturers to bring SuperSpeed USB technology to the market. Keynote speakers will address advancements offered by the new technology, and attendees will obtain information on best practices for incorporating SuperSpeed USB into their product roadmaps. In addition to technical sessions, an exhibit area will showcase the latest developments and early designs featuring SuperSpeed USB technology.

### **About Symwave, Inc.**

Symwave is a global fabless semiconductor company that designs, develops and markets high-performance analog/mixed-signal integrated circuits and related system software solutions. The Company specializes in the design and development of low-power, high-speed, standards-based Serial Physical Layer ICs (PHYs) and Analog Front End ICs (AFEs) leveraging its proprietary mixed-signal technology and silicon design capabilities. Symwave is focused on defining, developing and delivering best-in-class/first-in-class solutions for its customers,

leveraging an experienced world-class analog/mixed-signal IC design team and unique IP portfolio. Symwave is a privately held company funded in 2004 headquartered in Orange County, CA with a Design Center in Shenzhen, China, and offices in San Diego, CA, and Taipei, Taiwan. The company is backed by top-tier venture capital firms including Kodiak Venture Partners and CMEA Ventures, among others. Additional information is available at [www.symwave.com](http://www.symwave.com).

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